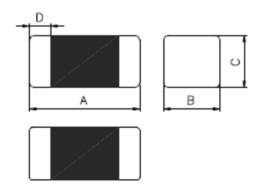


### **FEATRLRES**

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

## CONFIGRLRATIONS & DIMENSIONS ( unit in mm )



Size	Α	В	С	D
FCI1608	1.6±0.15	0.8±0.15	0.8±0.15	0.3±0.20

### **ELECTRICAL CHARACTERISTICS**

Part Number	Inductance(uH)		Q		Rated Current	DCR	SRF
Part Number	Tolerance	Test	min.	Test	(mA) max.	(Ω) max.	(MHz) min.
FCI1608F-47N□	0.047	60mV / 50M	10	50	50	0.30	260
FCI1608F-68N	0.068	60mV / 50M	10	50	50	0.30	250
FCI1608F-82N	0.082	60mV / 50M	10	50	50	0.30	245
FCI1608F-R10□	0.10	60mV / 25M	15	25	50	0.50	240
FCI1608F-R12	0.12	60mV / 25M	15	25	50	0.50	205
FCI1608F-R15	0.15	60mV / 25M	15	25	50	0.60	180
FCI1608F-R18□	0.18	60mV / 25M	15	25	50	0.60	165
FCI1608F-R22	0.22	60mV / 25M	15	25	50	0.80	150
FCI1608F-R27	0.27	60mV / 25M	15	25	50	0.80	136
FCI1608F-R33	0.33	60mV / 25M	15	25	35	0.85	125
FCI1608F-R39□	0.39	60mV / 25M	15	25	35	1.00	110
FCI1608F-R47	0.47	60mV / 25M	15	25	35	1.35	105
FCI1608F-R56	0.56	60mV / 25M	15	25	35	1.55	95

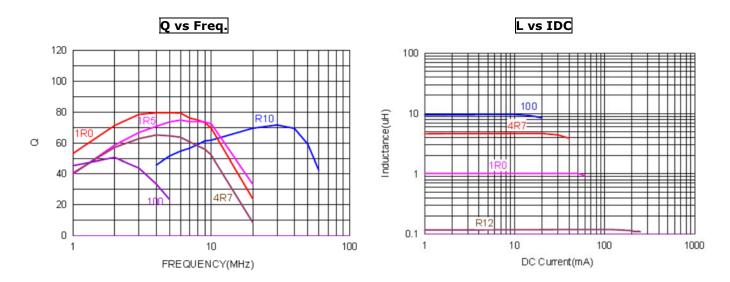
HSIA TECHNOLOGY CO.LTD. TEL:886-2-2999-6691 FAX: 2999-6692 Website:www.hsia.com.tw



FCI1608F-R68	0.68	60mV / 25M	15	25	35	1.70	80
FCI1608F-R82□	0.82	60mV / 25M	15	25	35	2.10	75
FCI1608F-1R0□	1.0	60mV / 10M	30	10	25	0.60	70
FCI1608F-1R5□	1.5	60mV / 10M	30	10	25	0.80	55
FCI1608F-1R8	1.8	60mV / 10M	30	10	25	0.95	50
FCI1608F-2R2□	2.2	60mV / 10M	30	10	15	1.15	45
FCI1608F-3R3	3.3	60mV / 10M	30	10	15	1.55	38
FCI1608F-4R7□	4.7	60mV / 10M	30	10	15	2.10	33
FCI1608F-100	10	60mV / 2M	30	2	15	2.55	17

- NOTE:  $\square$ : TOLERANCE  $K=\pm 10\%, L=\pm 15\%, M=\pm 20\%$
- Rated current: based on temperature rise test
- In compliance with EIA 595

# **Q vs Frequency,DC Bias Characteristics(Typical)**



## **Reliability and Test Condition**

Item	Performance	Test Condition			
Operating temperature	-40~+125℃ (Including self - temperature rise)				
Storage temperature	110~+40℃,50~60%RH (Product with taping) 240~+125℃ (on board)				
Electrical Performance Test					
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.			
DCR		CH16502,Agilent33420A Micro-Ohm Meter.			
Saturation Current (Isat)	Approximately△L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)			



Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(C)$ . 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test	·	
Life Test		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2 * R.H,  Temperature: 85℃±2℃  Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles  1. Baked at50°C for 25hrs, measured at room temperature after placing for 4 hrs.  2. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs.  3. Raise temperature to 65±2°C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25°C in 2.5hrs.  4. Keep at 25°C for 2 hrs then keep at -10°C for 3 hrs  4. Keep at 25°C 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2℃ 30±5min Step2: 25±2℃ ≦0.5min Step3: 125±2℃ 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes  Equipment: Vibration checker  Total Amplitude:1.52mm±10%  Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm  Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.
Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type         Peak value (g's)         Normal duration (D) (ms)         Wave form         Velocity change (Vi)ft/sec           SMD         50         11         Half-sine         11.3           Lead         50         11         Half-sine         11.3
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ∘ Flux for lead free: Rosin. 9.5% ∘ Dip time: 4±1sec ∘ Depth: completely cover the termination
Resistance to Soldering Heat		Depth: completely cover the termination  Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate   Number of heat cycles    260 ±5   10 ±1   25mm/s ±6 mm/s   1
		(solder temp) 10 ±1 25mm/s ±0 mm/s 1



Appearance: No damage.

Impedance: within±15% of initial value
Inductance: within±10% of initial value
Q: Shall not exceed the specification value and shall not exceed the specification value e

Terminal
Strength

Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.

DUT

wide

press tool

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.